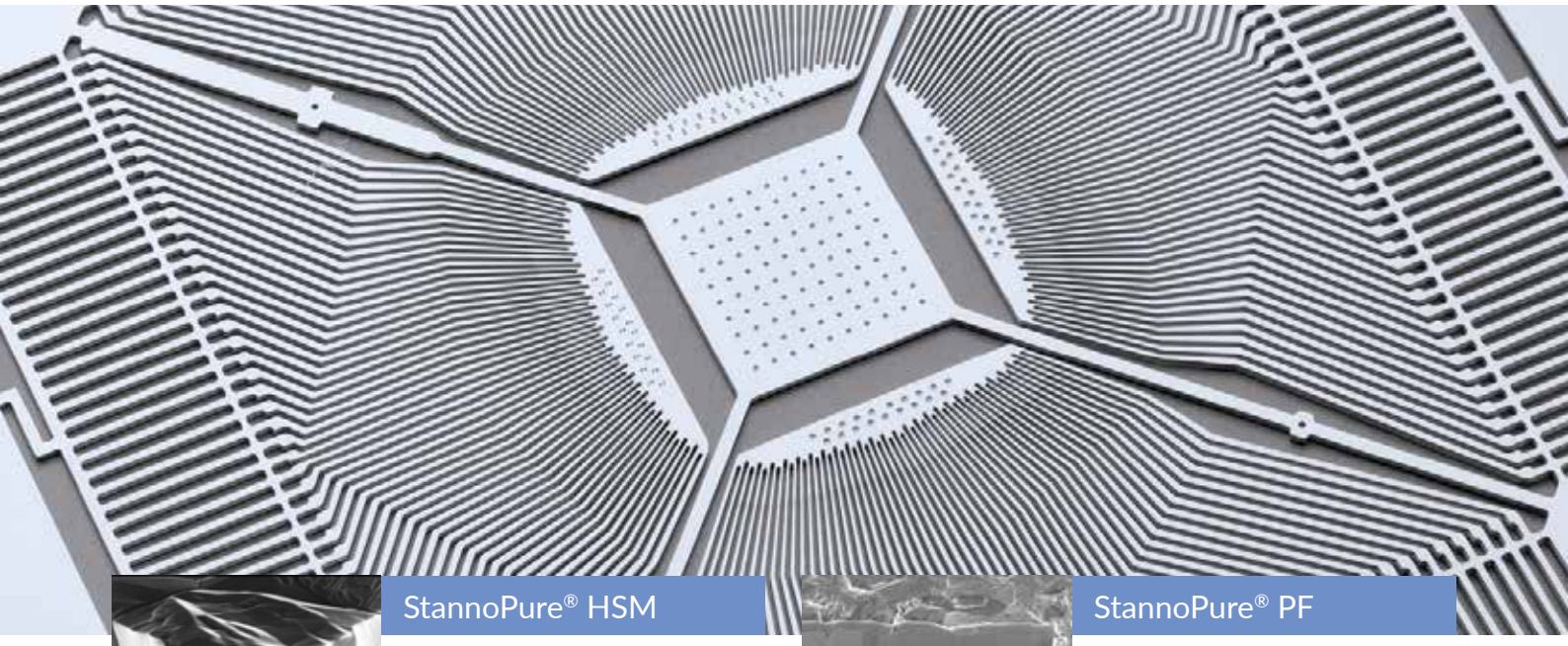
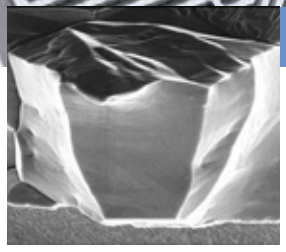
StannoPure®

A product family for pure tin deposits from matt to bright deposits

Electronics | Functional electronic coatings | atotech.com

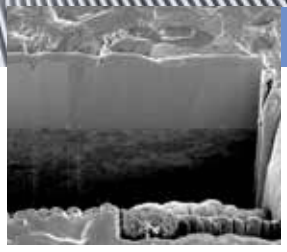




StannoPure® HSM

Our Evergreen – matt tin

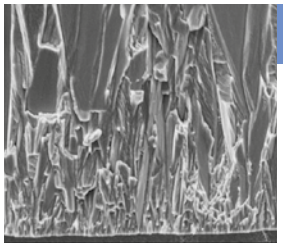
Qualified at many major lead frame and connector manufacturer – for high speed and high reliability deposits



StannoPure® PF

For sophisticated designs – matt tin

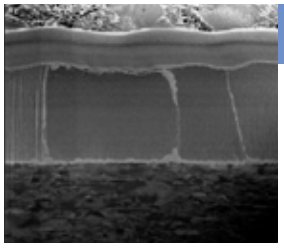
Excellent coverage for even the most difficult designs, developed to deposit tin also on low current density areas



StannoPure® HSB

Bright tin

High purity and bright deposition process for all tool types. Excellent solderability. Qualified at major connector manufacturers



StannoPure® 100/3000

Simplicity – matt tin

Stannopure 100 resp. 3000 is easy to control and an extremely stable process chemistry. Top seller in China

StannoPure® product family

- Deposits a pure tin layer from MSA based electrolytes
- Accepted by major connector, wire and lead frame manufacturers
- For all types of plating tools – from reel to reel to rack and barrel applications
- For high speed and low speed applications
- Outstanding stability and longevity of electrolytes
- Low whisker propensity
- Excellent solderability
- Ideally combined with our Protectostan® and PostDip SN products to preserve excellence
- Free of fluoroborate and NPE

ATOTECH

StannoPure® family – pure tin deposition solution for lead frames, connectors and more

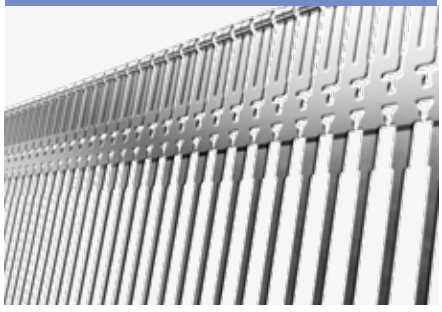
Product	StannoPure® HSM	StannoPure® PF	StannoPure® 100/3000	StannoPure® HSB
Appearance	Matt	Matt	Matt	Bright
Application	All tools	All tools	Reel to Reel	All tools
Current density range ASD	0.5 – 50	2.5 – 25	5 – 25	1 – 50
Deposition speed µm/min	0.2 – 20	1 – 10	2 – 10	0.4 – 20
Grain size µm	3 – 8	3 – 8	3 – 8	> 1
Roughness RSAI %*	40 – 60	30 – 50	30 – 40	15
Purity %	> 99.90	> 99.90	> 99.90	> 99.90
Solderability	Very good	Very good	Excellent	Excellent
Cutting edge	High speed and low roughness	Perfect coverage in low current density areas & excellent stability	Excellent stability and simplicity; low foam	No sticking of parts in barrel applications

* RSAI = Relative surface area increase compared to a totally flat surface, measured by interference micorscopy

Lead frames / ICs

Wires

Connectors



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